

IN THE CLAIMS

Please cancel claims 21 and 41-42 and amend claims 1, 5, 9, 15 and 17-18 to read as shown below by substituting the claims below for claims having the same number as follows. Pursuant to 37 C.F.R. §1.121, a marked-up version of the following claims is provided at the end of this Amendment as Exhibit B.

B3
1. (Amended) A device comprising:

a package module including a substrate having a standard package footprint;
an unpackaged semiconductor die directly attached to the package module, the
unpackaged semiconductor die encapsulated onto the package module in a structure having a
substantially rectangular footprint; and
a packaged semiconductor die attached to the package module.

*not clearly defined in the claim.
Examiner assumed
structure = package module*

B4 (ind 37)
5. (Amended) The device as in claim 1, wherein a plurality of packaged semiconductors are attached to the package module.

B5 (ind 37)
9. (Twice Amended) The device as in claim 1, wherein the encapsulated structure has a footprint greater than the footprint of the unpackaged semiconductor die.

B6
15. (Amended) A device comprising:

a package module sized to be interchangeable with standard package sizes;
a graphics-processing die directly attached to the package module, the graphics-processing die encapsulated on the package module in a structure having a rectangular footprint;
and
a packaged memory die attached to the package module.

B7 (ind 57)
17. (Amended) The device as in claim 15, wherein a plurality of packaged memory are attached to the package module.

18. (Amended) The device as in claim 15, wherein directly attached includes the graphics processing die being wire bonded to the package module.